Errata TMS320F28002x Real-Time MCUs Silicon Errata Silicon Revisions A, 0



ABSTRACT

This document describes the known exceptions to the functional specifications (advisories). This document may also contain usage notes. Usage notes describe situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness.

Table of Contents

1 Usage Notes and Advisories Matrices	2
1.1 Üsage Notes Matrix	2
1.2 Advisories Matrix	2
2 Nomenclature, Package Symbolization, and Revision Identification	3
2.1 Device and Development-Support Tool Nomenclature	3
2.2 Devices Supported	3
2.3 Package Symbolization and Revision Identification	4
3 Silicon Revision A Usage Notes and Advisories	5
3.1 Silicon Revision A Usage Notes	5
3.2 Silicon Revision A Advisories	7
4 Silicon Revision 0 Usage Notes and Advisories	
4.1 Silicon Revision 0 Usage Notes	24
4.2 Silicon Revision 0 Advisories	
5 Documentation Support	
6 Trademarks	25
7 Revision History	

List of Figures

Figure 2-1. Package Symbolization for PM and PN Packages	4
Figure 2-2. Package Symbolization for PT Package	4
Figure 3-1. Undesired Trip Event and Blanking Window Expiration	12
Figure 3-2. Resulting Undesired ePWM Outputs Possible	12
Figure 3-3. Pipeline Diagram of the Issue When There are no Stalls in the Pipeline	14
Figure 3-4. Pipeline Diagram of the Issue if There is a Stall in the E3 Slot of the Instruction I1	15
Figure 3-5. Pipeline Diagram With Workaround in Place	16

List of Tables

Table 1-1. Usage Notes Matrix	2
Table 1-2. Advisories Matrix	2
Table 2-1. Revision Identification	4
Table 3-1. Data Rise Time Requirements for C2000 as Target Transmitter with Standard-Mode Host	17
Table 3-2. Pullup Resistor (R _n) Values for Common Bus Capacitances (C _h)	18
Table 3-3. Memories Impacted by Advisory	20

1



1 Usage Notes and Advisories Matrices

Table 1-1 lists all usage notes and the applicable silicon revisions. Table 1-2 lists all advisories, modules affected, and the applicable silicon revisions.

1.1 Usage Notes Matrix

Table 1-1. Usage Notes Matrix			
NUMBER	TITLE	SILI REVIS AFFE	CON SIONS CTED
		0	Α
Section 3.1.1	PIE: Spurious Nested Interrupt After Back-to-Back PIEACK Write and Manual CPU Interrupt Mask Clear	Yes	Yes
Section 3.1.2	Caution While Using Nested Interrupts	Yes	Yes
Section 3.1.3	Security: The primary layer of defense is securing the boundary of the chip, which begins with enabling JTAGLOCK and Zero-pin Boot to Flash feature	Yes	Yes

1.2 Advisories Matrix

Table 1-2. Advisories Matrix

MODULE	DESCRIPTION	SILI REVIS AFFE	CON SIONS CTED
		0	Α
ADC	ADC: Interrupts may Stop if INTxCONT (Continue-to-Interrupt Mode) is not Set	Yes	Yes
ADC	ADC: DMA Read of Stale Result	Yes	Yes
Boot ROM, MPOST	Boot-ROM, MPOST: Longer Boot Time With MPOST Enabled	Yes	Yes
BOR	BOR: VDDIO Between 2.45 V and 3.0 V can Result in Multiple XRSn Pulses	Yes	Yes
DCAN	During DCAN FIFO Mode, Received Messages May be Placed Out of Order in the FIFO Buffer	Yes	Yes
ePWM	ePWM: An ePWM Glitch can Occur if a Trip Remains Active at the End of the Blanking Window	Yes	Yes
ePWM	ePWM: Event Latch (DCxEVTxLAT) of "DC Event-Based CBC Trip" May not Extend Trigger Pulse as Expected When Asynchronous Path is Selected	Yes	No
ePWM	ePWM: Trip Events Will Not be Filtered by the Blanking Window for the First 3 Cycles After the Start of a Blanking Window	Yes	Yes
eQEP	eQEP: Position Counter Incorrectly Reset on Direction Change During Index	Yes	Yes
FPU	FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation	Yes	Yes
12C	I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation	Yes	Yes
LIN	LIN: Inconsistent Sync Field Error (ISFE) Flag/Interrupt Not Set When Sync Field is Erroneous	Yes	Yes
Memory	Memory: Prefetching Beyond Valid Memory	Yes	Yes
SYSTEM	SYSTEM: HIC Illegal Read Error Flag Does not Get Asserted in Pagesel=0 Mode	Yes	Yes
SYSTEM	SYSTEM: Multiple Successive Writes to CLKSRCCTL1 Can Cause a System Hang	Yes	Yes
Diagnostics	Avoiding Spurious Interrupts While Using HWBIST	Yes	Yes
PLL	PLL Reference Clock Lost Detection: Missing Clock Flag may be Incorrectly Activated	Yes	Yes

2

2 Nomenclature, Package Symbolization, and Revision Identification 2.1 Device and Development-Support Tool Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all DSP devices and support tools. Each DSP commercial family member has one of three prefixes: TMX, TMP, or TMS (for example, TMS320F280025C). Texas Instruments recommends two of three possible prefix designators for its support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX and TMDX) through fully qualified production devices and tools (TMS and TMDS).

Device development evolutionary flow:

- **TMX** Experimental device that is not necessarily representative of the final device's electrical specifications and may not use production assembly flow.
- **TMP** Prototype device that is not necessarily the final silicon die and may not necessarily meet final electrical specifications.
- TMS Production version of the silicon die that is fully qualified.

Support tool development evolutionary flow:

TMDX Development-support product that has not yet completed Texas Instruments internal qualification testing.

TMDS Fully-qualified development-support product.

TMX and TMP devices and TMDX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

Production devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (X or P) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

2.2 Devices Supported

This document supports the following devices:

- TMS320F280025
- TMS320F280025-Q1
- TMS320F280025C
- TMS320F280025C-Q1
- TMS320F280023
- TMS320F280023-Q1
- TMS320F280023C
- TMS320F280021
- TMS320F280021-Q1



2.3 Package Symbolization and Revision Identification

Figure 2-1 and Figure 2-2 show the package symbolization. Table 2-1 lists the silicon revision codes.



G4 = Green (Low Halogen and RoHS-compliant)





Figure 2-2.	Package	Symbolization	for PT	Package
-------------	---------	---------------	--------	---------

SILICON REVISION CODE	SILICON REVISION	REVID ⁽¹⁾ Address: 0x5D00C	COMMENTS ⁽²⁾
Blank	0	0x0000 0000	This silicon revision is available as TMX.
А	А	0x0000 0001	This silicon revision is available as TMX and TMS.

Table 2-1. Revision Identification

(1) Silicon Revision ID

4

(2) For orderable device numbers, see the PACKAGING INFORMATION table in the *TMS320F28002x Real-Time Microcontrollers* data sheet.



3 Silicon Revision A Usage Notes and Advisories 3.1 Silicon Revision A Usage Notes

This section lists all the usage notes that are applicable to silicon revision A [and earlier silicon revisions].

3.1.1 PIE: Spurious Nested Interrupt After Back-to-Back PIEACK Write and Manual CPU Interrupt Mask Clear

Revisions Affected: 0, A

Certain code sequences used for nested interrupts allow the CPU and PIE to enter an inconsistent state that can trigger an unwanted interrupt. The conditions required to enter this state are:

- 1. A PIEACK clear is followed immediately by a global interrupt enable (EINT or asm(" CLRC INTM")).
- 2. A nested interrupt clears one or more PIEIER bits for its group.

Whether the unwanted interrupt is triggered depends on the configuration and timing of the other interrupts in the system. This is expected to be a rare or nonexistent event in most applications. If it happens, the unwanted interrupt will be the first one in the nested interrupt's PIE group, and will be triggered after the nested interrupt reenables CPU interrupts (EINT or asm(" CLRC INTM")).

Workaround: Add a NOP between the PIEACK write and the CPU interrupt enable. Example code is shown below.

```
//Bad interrupt nesting code
PieCtrlRegs.PIEACK.all = 0xFFFF;
EINT; //Enable nesting in the PIE
//Good interrupt nesting code
PieCtrlRegs.PIEACK.all = 0xFFFF;
asm(" NOP"); //Wait for PIEACK to exit the pipeline
EINT; //Enable nesting in the CPU
```

3.1.2 Caution While Using Nested Interrupts

Revisions Affected: 0, A

If the user is enabling interrupts using the EINT instruction inside an interrupt service routine (ISR) in order to use the nesting feature, then the user must disable the interrupts before exiting the ISR. Failing to do so may cause undefined behavior of CPU execution.



3.1.3 Security: The primary layer of defense is securing the boundary of the chip, which begins with enabling JTAGLOCK and Zero-pin Boot to Flash feature

Revisions Affected: 0, A

Device security relies on the premise that unauthorized code is not allowed to enter the device and execute under any circumstances. To that end, the device provides two features that a user concerned about security should always enable.

• JTAGLOCK

When enabled in the USER OTP area of flash, the JTAGLOCK feature disables JTAG access (for example, debugger connection) to resources on the device, blocking an unauthorized party from using the JTAG interface to download any code into the device. When JTAGLOCK is enabled, the user can still allow an authorized party to unlock it by entering a password, or they can lock it permanently by programming a password value of all all-zeros.

Zero-pin Boot to Flash

The external bootloaders built into the TI ROM do not perform any authentication of the downloaded code. Enabling the Zero-pin boot option along with a flash boot mode in the USER OTP blocks all pin-based external bootloader options (for example, SCI, CAN, Parallel) from running at boot by forcing the boot process to jump immediately to internal flash after the base boot ROM execution concludes. For highest security, the Secure Flash boot mode can be chosen. This enables a pre-check of the flash code by the base boot ROM before jumping to it.

If JTAG is locked permanently and the Zero-pin Boot to Flash option is enabled, programming tools that communicate with the device through JTAG or the built-in bootloaders will not work. If the ability to perform firmware upgrades is desired, the user must pre-store code in flash to securely manage and perform the update.

3.2 Silicon Revision A Advisories

This section lists all the advisories that are applicable to silicon revision A [and earlier silicon revisions].

Advisory	ADC: Interrupts may Stop if INTxCONT (Continue-to-Interrupt Mode) is not Set
Revisions Affected	0, A
Details	If ADCINTSELxNx[INTxCONT] = 0, then interrupts will stop when the ADCINTFLG is set and no additional ADC interrupts will occur.
	When an ADC interrupt occurs simultaneously with a software write of the ADCINTFLGCLR register, the ADCINTFLG will unexpectedly remain set, blocking future ADC interrupts.
Workaround	 Use Continue-to-Interrupt Mode to prevent the ADCINTFLG from blocking additional ADC interrupts:
	ADCINTSEL1N2[INT1CONT] = 1; ADCINTSEL1N2[INT2CONT] = 1; ADCINTSEL3N4[INT3CONT] = 1; ADCINTSEL3N4[INT4CONT] = 1;
	 Ensure there is always sufficient time to service the ADC ISR and clear the ADCINTFLG before the next ADC interrupt occurs to avoid this condition. Check for an overflow condition in the ISR when clearing the ADCINTFLG. Check ADCINTOVF immediately after writing to ADCINTFLGCLR; if it is set, then write ADCINTFLGCLR a second time to ensure the ADCINTFLG is cleared. The ADCINTOVF register will be set, indicating an ADC conversion interrupt was lost.
	<pre>AdcaRegs.ADCINTFLGCLR.bit.ADCINT1 = 1; //clear INT1 flag if(1 == AdcaRegs.ADCINTOVF.bit.ADCINT1) //ADCINT overflow { AdcaRegs.ADCINTFLGCLR.bit.ADCINT1 = 1; //clear INT1 again // If the ADCINTOVF condition will be ignored by the application // If the ADCINTOVF condition will be ignored by the application // If there is a ADCINTOVF handling routine, then either insert // If there is a ADCINTOVF handling routine, then either insert // If there is a ADCINTOVF handling routine will detect the // the ADCINTOVF here so the external routine will detect the // condition. // AdcaRegs.ADCINTOVFCLR.bit.ADCINT1 = 1; // clear OVF } </pre>

7



Advisory	ADC: DMA Read of Stale Result	
Revisions Affected	0, A	
Details	 The ADCINT flag can be set before the ADCRESULT value is latched (see the t_{LAT} and t_{INT(LATE)} columns in the ADC Timings table of the <i>TMS320F28002x Real-Time Microcontrollers</i> data sheet). The DMA can read the ADCRESULT value as soon as 3 cycles after the ADCINT trigger is set. As a result, the DMA could read a prior ADCRESULT value when the user expects the latest result if all of the following are true: The ADC is in late interrupt mode. The ADC operates in a mode where t_{INT(LATE)} occurs 3 or more cycles before t_{LAT} (ADCCTL2 [PRESCALE] > 2). The DMA is triggered from the ADCINT signal. The DMA immediately reads the ADCRESULT value associated with that ADCINT signal without reading any other values first. The DMA was idle when it received the ADCINT trigger. 	
	 Only the DMA reads listed above could result in reads of stale data; the following non-DMA methods will always read the expected data: The ADCINT flag triggers a CLA task. The ADCINT flag triggers a CPU ISR. The CPU polls the ADCINT flag. 	
Workaround	Trigger two DMA channels from the ADCINT flag. The first channel acts as a dummy transaction. This will result in enough delay that the second channel will always read the fresh ADC result.	

Advisory	Boot-ROM, MPOST: Longer Boot Time With MPOST Enabled
Revisions Affected	0, A
Details	When MPOST functionality is enabled through user OTP, the boot-ROM execution time is around 5 seconds. This is because the boot-ROM executes MPOST with INTOSC clock of 10 MHz, which results in longer boot time.
Workaround	Avoid using boot-ROM supported MPOST and perform necessary memory self-tests as part of application initialization.



Advisory	BOR: VDDIO Between 2.45 V and 3.0 V can Result in Multiple XRSn Pulses	
Revisions Affected	0, A	
Details	The BOR can generate repeating XRSn assertions and deassertions when the VDDIO supply voltage is between 2.45 V and 3.0 V. It is recommended that the XRSn pin <i>not</i> be used directly as a reset to any other devices in the system.	
	The F28002x BOR is effective for internally holding the device in a known reset state, even when these XRSn pulses are occurring. The device will not branch to application code or bootloaders, and all other pins will be held in their reset state until the VDDIO supply rises above 3.0 V.	
Workarounds	 Ignore the extra XRSn transitions during power up, power down, and BOR events. The extra XRSn pulses will have no effect on the F28002x device operation itself. If XRSn pulses would cause undesired system behavior with other system components, then do not use XRSn to drive other devices. An external voltage supervisor can be used for these applications. For applications that need to avoid these pulses during normal power up and power down: Power up: Follow the t_{VDDIO-RAMP} requirement in the Recommended Operating Conditions table of the <i>TMS320F28002x Real-Time Microcontrollers</i> data sheet; no extra XRSn low pulses will occur. Power Down: To avoid any deassertion of XRSn during power down, design the power supply so that VDDIO passes through the range from 3.0 V to 2.45 V within 25 µs. If some voltage rise on XRSn is acceptable, then the time constant of the RC circuit implemented on XRSn can be calculated to ensure the voltage does not rise above a system-specified threshold. 	

Advisory	During DCAN FIFO Mode, Received Messages May be Placed Out of Order in the FIFO Buffer	
Revisions Affected	0, A	
Details	In DCAN FIFO mode, received messages with the same arbitration and mask IDs are supposed to be placed in the FIFO in the order in which they are received. The CPU then retrieves the received messages from the FIFO via the IF1/IF2 interface registers. Some messages may be placed in the FIFO out of the order in which they were received. If the order of the messages is critical to the application for processing, then this behavior will prevent the proper use of the DCAN FIFO mode.	
Workaround	Use the DMA to read out the FIFO via the IF3 register. Each time a message is received into the FIFO, the data is also copied to the IF3 register, and a DMA request Is generated to the DMA module to read out the data.	



Silicon Revision A Usage Notes and Advisories Advisory ePWM: An ePWM Glitch can Occur if a Trip Remains Active at the End of the Blanking Window **Revisions Affected** 0. A Details The blanking window is typically used to mask any PWM trip events during transitions which would be false trips to the system. If an ePWM trip event remains active for less than three ePWM clocks after the end of the blanking window cycles, there can be an undesired glitch at the ePWM output. Figure 3-1 illustrates the time period which could result in an undesired ePWM output. 3 ePWM cycles Blanking Window Blanking Window **Blanking Complete** Active Undesired Trip Trip Source Trip Active Trip Inactive Active-to-Inactive Transition Figure 3-1. Undesired Trip Event and Blanking Window Expiration Figure 3-2 illustrates the two potential ePWM outputs possible if the trip event ends within 1 cycle before or 3 cycles after the blanking window closes. ePWM Output Pin (Possibility A) Active Trip Active Trip (Trip interrupt will be issued) State State State State ePWM Output Pin (Possibility B) Active Trip Active State (Trip interrupt will not be issued) State State Figure 3-2. Resulting Undesired ePWM Outputs Possible Workaround Extend or reduce the blanking window to avoid any undesired trip action. ePWM: Trip Events Will Not be Filtered by the Blanking Window for the First Advisory 3 Cycles After the Start of a Blanking Window **Revisions Affected** 0. A Details The Blanking Window will not blank trip events for the first 3 cycles after the start of a Blanking Window. DCEVTFILT may continue to reflect changes in the DCxEVTy signals. If DCEVTFILT is enabled, this may impact subsequent subsystems that are configured (for

Workaround Start the Blanking Window 3 cycles before blanking is required. If a Blanking Window is needed at a period boundary, start the Blanking Window 3 cycles before the beginning of the next period. This works because Blanking Windows persist across period boundaries.

example, the Trip Zone submodule, TZ interrupts, ADC SOC, or the PWM output).

Advisory	eQEP: Position Counter Incorrectly Reset on Direction Change During Index							
Revisions Affected	0, A							
Details	While using the PCRM = 0 configuration, if the direction change occurs when the index input is active, the position counter (QPOSCNT) could be reset erroneously, resulting in an unexpected change in the counter value. This could result in a change of up to ± 4 counts from the expected value of the position counter and lead to unexpected subsequent setting of the error flags.							
	While using the PCRM = 0 configuration [that is, Position Counter Reset on Index Event (QEPCTL[PCRM] = 00)], if the index event occurs during the forward movement, then the position counter is reset to 0 on the next eQEP clock. If the index event occurs during the reverse movement, then the position counter is reset to the value in the QPOSMAX register on the next eQEP clock. The eQEP peripheral records the occurrence of the first index marker (QEPSTS[FIMF]) and direction on the first index event marker (QEPSTS[FIDF]) in QEPSTS registers. It also remembers the quadrature edge on the first index marker so that same relative quadrature transition is used for index event reset operation.							
	If the direction change occurs while the index pulse is active, the module would still continue to look for the relative quadrature transition for performing the position counter reset. This results in an unexpected change in the position counter value.							
	The next index event without a simultaneous direction change will reset the counter properly and work as expected.							
Workarounds	Do not use the PCRM = 0 configuration if the direction change could occur while the index is active and the resultant change of the position counter value could affect the application.							
	Other options for performing position counter reset, if appropriate for the application [such as Index Event Initialization (IEI)], do not have this issue.							



Advisory FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation

Revisions Affected 0, A

Details

This advisory applies when a multicycle (2p) FPU instruction is followed by a FPU-to-CPU register transfer. If the FPU-to-CPU read instruction source register is the same as the 2p instruction destination, then the read may be of the value of the FPU register before the 2p instruction completes. This occurs because the 2p instructions rely on data-forwarding of the result during the E3 phase of the pipeline. If a pipeline stall happens to occur in the E3 phase, the result does not get forwarded in time for the read instruction.

The 2p instructions impacted by this advisory are MPYF32, ADDF32, SUBF32, and MACF32. The destination of the FPU register read must be a CPU register (ACC, P, T, XAR0...XAR7). This advisory does not apply if the register read is a FPU-to-FPU register transfer.

In the example below, the 2p instruction, MPYF32, uses R6H as its destination. The FPU register read, MOV32, uses the same register, R6H, as its source, and a CPU register as the destination. If a stall occurs in the E3 pipeline phase, then MOV32 will read the value of R6H before the MPYF32 instruction completes.

Example of Problem:

MPYF32 R6H, R5H, R0H	; 2p FPU instruction that writes to R6H
F32TOUI16R R3H, R4H	; delay slot
MOV32 &SP, R2H MOV32 @XAR3, R6H	; alignment cycle ; FPU register read of R6H

Figure 3-3 shows the pipeline diagram of the issue when there are no stalls in the pipeline.

	Instruction	F1	F2	D1	D2	R1	R2	Е	w			
		1	FPU pipeline-		FPU pipeline>		R1	R2	E1	E2	E3	Comments
Il	MPYF32 R6H, R5H, R0H MOV32 *XAR7++, R4H	Il										
I2	F32TOUI16R R3H, R4H	I2	I1									
I3	ADDF32 R3H, R2H, R0H MOV32 *SP, R2H	I3	I2	Il								
I4	MOV32 @XAR3, R6H	I4	I3	I2	I1							
			I4	I3	I2	I1						
				I4	I3	I2	I1					
					I4	I3	I2	I1				
						I4	I3	I2	I1			
							<u>14</u>	I3	12	<u>11</u>	I4 samples the result as it enters the R2 phase. The product R6H=R5H*R0H (II) finishes computing in the E3 phase, but is forwarded as an operand to I4. This makes I4 appear to be a 2p instruction, but I4 actually takes 3p cycles to compute.	
								I4	I3	I2		
									I4	I3		

Figure 3-3. Pipeline Diagram of the Issue When There are no Stalls in the Pipeline



Advisory (continued) FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation

	1										1
	Instruction	F1	F2	D1	D2	R1	R2	E	w		Comments
			FPU pip	eline>	•	R1	R2	E1	E2	E3	conments
	MPYF32 R6H, R5H, R0H	-									
11	MOV32 *XAR7++, R4H	11									
I2	F32TOUI16R R3H, R4H	I2	I1								
	ADDF32 R3H, R2H, R0H	* 0									
13	MOV32 *SP, R2H	13	12	11							
I4	MOV32 @XAR3, R6H	I4	I3	I2	I1						
			I4	I3	I2	I1					
				I4	I3	I2	I1				
					I4	I3	I2	I1			
						I4	I3	I2	I1		
							<u>14</u>	IJ	I2	I1 (STALL)	I4 samples the result as it enters the R2 phase, but I1 is stalled in E3 and is unable to forward the product of R5H*R0H to I4 (R6H does not have the product yet due to a design bug). So, I4 reads the old value of R6H.
							14	13	I2	Il	There is no change in the pipeline as it was stalled in the previous cycle. I4 had already sampled the old value of R6H in the previous cycle.
								Ι4	Ι3	I2	Stall over

Figure 3-4 shows the pipeline diagram of the issue if there is a stall in the E3 slot of the instruction I1.

Figure 3-4. Pipeline Diagram of the Issue if There is a Stall in the E3 Slot of the Instruction I1

Workaround

Treat MPYF32, ADDF32, SUBF32, and MACF32 in this scenario as 3p-cycle instructions. Three NOPs or non-conflicting instructions must be placed in the delay slot of the instruction.

The C28x Code Generation Tools v.6.2.0 and later will both generate the correct instruction sequence and detect the error in assembly code. In previous versions, v6.0.5 (for the 6.0.x branch) and v.6.1.2 (for the 6.1.x branch), the compiler will generate the correct instruction sequence but the assembler will not detect the error in assembly code.

Example of Workaround:

MPYF32 R6H, R5H, R0H MOV32 *XAR7++, R4H F32TOUI16R R3H, R4H ADDF32 R2H R2H R0H	; 3p FPU instruction that writes to R6H ; delay slot
MOV32 *SP, R2H	; delay slot
NOP	; alignment cycle
MOV32 @XAR3, R6H	; FPU register read of R6H

Figure 3-5 shows the pipeline diagram with the workaround in place.



Advisory (continued) FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation

	Instruction	F1	F2	D1	D2	R1	R2	E	w		
		FPU pip		PU pipeline>		R1	R2	E1	E2	E3	Comments
I1	MPYF32 R6H, R5H, R0H MOV32 *XAR7++, R4H	11									
I2	F32TOUI16R R3H, R4H	I2	I1								
I3	ADDF32 R3H, R2H, R0H MOV32 *SP, R2H	I3	I2	Il							
I4	NOP	I4	I3	I2	I1						
I5	MOV32 @XAR3, R6H	I5	I4	I3	I2	I1					
			I5	I4	I3	I2	I1				
				I5	I4	I3	I2	I1			
					I5	I4	I3	I2	I1		
						I5	I4	I3	I2	I1 (STALL)	Due to one extra NOP, I5 does not reach R2 when I1 enters E3; thus, forwarding is not needed.
						15	I4	I3	I2	Il	There is no change due to the stall in the previous cycle.
							15	I4	I3	I2	Il moves out of E3 and I5 moves to R2. R6H has the result of R5H*R0H and is read by I5. There is no need to forward the result in this case.
								I5	I4	I3	

Figure 3-5. Pipeline Diagram With Workaround in Place

Advisory	I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation									
Revision Affected	0, A	L.								
Details	The I2C peripheral present on the MCU is a Fast-mode device; it will clock-stretch the SCL (Clock) line when used with a Standard-mode host.									
	There is a requirement from the I2C Specification for a Fast-mode device used in a Standard-mode system to meet $t_{SU:DAT}$ (data set-up time) + $t_{r(max)}$ (rise time) before releasing the SCL line. See Footnote 4 of the "Characteristics of the SDA and SCI bus lines for Standard, Fast, and Fast-mode Plus I ² C-bus devices" table in the NX Semiconductors <i>I</i> ² C-bus specification and user manual (UM10204)									
	However, the C2000 I2C clock-stretches the SCL line by a fixed amount = $6 * f_{mod}$ Clock (I2C Clock rate of the C2000) in the above scenario. When the C2000 TM microcontroller acting as a target transmitter with a Standard-mode host, it is possible for the clock line (SCL) to be released by the C2000 before the data (SDA) is ready, if the t _r of SDA is to long.									
	The "Pull-up resistor sizing" section in the NXP Semiconductors I^2C -bus specification and user manual (UM10204) gives more details on choosing the appropriate PU resistor (R_p), based on the rise time (t_r) and bus capacitance (C_b) shown in Equation 1.									
		$R_{p(max)} =$	$= \frac{t_r}{0.8473 \times C_b}$			(1)				
 Reducing t_r with a strong pullup In order to ensure that t_{SU:DAT} + t_{r(max)} is met, the user can configure the resistance on the SDA line such that it meets the constraints listed in the Rise Time Requirement column of Table 3-1 based on the value of f_{mod} system. This will ensure that the data present on the SDA line is valid w C2000 releases the SCL signal. 						ure the pullup d in the SDA Data of f _{mod} Clock in their valid when the				
Table 3-2 gives suggested R_p resistor values for a given f_{mod} Clock (MHz) and C_b (b capacitance). For other values of C_b , please use Equation 1 to calculate the value or R_p needed in the system.						k (MHz) and C _b (bus alculate the value of				
		Table 3-1.	Data Rise Time I	Requirements fo Standard-Mode	r C2000 as Targe e Host	et Transmitter with				
				SCL Clock-	Data Set-up					

f _{mod} Clock (MHz)	f _{mod} Period (ns)	SCL Clock- Stretch Delay from C2000 I2C (ns): (6*f _{mod} Clock)	Data Set-up Time (ns): t _{SU:DAT} (Standard Mode)	SDA Data Rise Time Requirement (ns): t _r
7	142.9	857		607
8	125	750		500
9	111	666	250	416
10	100	600	230	350
11	90.9	545		295
12	83.3	500		250



Advisory (continued) I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation

Table 3	Table 3-2. Pullup Resistor (R _p) Values for Common Bus Capacitances (C _b)						
f _{mod} Clock (MHz)	SDA Data Rise Time Requirement (ns): t _r	R _p (kΩ) for C _b = 100 pF	R _p (kΩ) for C _b = 200 pF	R _p (kΩ) for C _b = 300 pF	R _p (kΩ) for C _b = 400 pF		
7	607	7.1	3.5	2.3	1.7		
8	500	5.9	2.9	1.9	1.4		
9	416	4.9	2.4	1.6	1.2		
10	350	4.1	2.0	1.3	1.0		
11	295	3.4	1.7	1.1	0.8		
12	250	2.9	1.4	0.9	0.7		

2. t_r = 1000 ns

This workaround is not preferred due to restrictions in general I2C usage, use Workaround 1 when possible.

If the system is such that it requires 1000 ns of rise time on the SDA line, the C2000 I2C f_{mod} Clock can be configured to 4.8 MHz so the clock-stretching (6 * f_{mod} Clock) satisfies this requirement. This results in $t_r = (1/4.8 \text{ MHz}) * 6 = 1000 \text{ ns}$. This workaround is only valid in systems where the C2000 I2C is the target on the I2C bus. Note that 4.8 MHz is outside the data sheet's required range of 7 MHz to 12 MHz for f_{mod} Clock. Using f_{mod} at 4.8 MHz, even though it is outside of the data sheet's required range, will work for the C2000 I2C in Target mode on a Standard-mode host bus. Using $f_{mod} = 4.8$ MHz in any other configurations except the one listed in this workaround will cause other timing parameters to be violated and is not allowed.

Advisory	LIN: Inconsistent Sync Field Error (ISFE) Flag/Interrupt Not Set When Sync Field i Erroneous						
Revisions Affected	0, A						
Details	During LIN communications, if the Sync field received (on RX) is erroneous (that is, if the Sync field receives any value other than 0x55), the LIN does not set the ISFE Flag in the SCIFLR.ISFE register or trigger the ISFE interrupt. Communication gets terminated without data being received or the RX receive interrupt being set. There is no way for an application to detect an error in the Sync field. The application can detect if the Sync field is completely blank or if the Sync field is not received within the given tolerances (as explained in the <i>TMS320F28002x Real-Time Microcontrollers Technical Reference Manual</i>), but the application cannot detect any error in the value of Sync field.						
Workarounds	Method 1: Keep polling the SCIFLR.RXRDY flag and time out if it is not set within a certain amount of time.						
	Use the following steps as a guideline:						
	 Poll for the SCIFLR.BUSY flag to set. Once the BUSY flag goes high, poll for the SCIFLR.RXRDY flag. Concurrently within this loop, also have a SW timeout, which times out and exits the loop if the RXRDY flag is not set within a user-defined time interval. 						
	Method 2: Configure the CPU timer to interrupt if the RX interrupt is not triggered. This method does not use CPU bandwidth.						
	Use the following steps as a guideline:						
	 Configure XINT to trigger an ISR when the LINRX goes from high to low (indicating LIN is busy). Inside the XINT ISR, configure the CPU timer, which starts timing the frame completion. If the frame is received correctly with the correct Sync field, it should trigger the LIN RX ISR, inside which you can turn off the timer so that you do not get a false timeout. If the frame is not received correctly, it does not trigger the LIN RX ISR but triggers the CPU timer ISR (timeout occurred), which indicates an error in the Sync field. 						



Advisory	Memory: Prefetching Beyond Valid Memory						
Revisions Affected	0, A						
Details	The C28x CPU prefetches inst the prefetch occurs past the er opcode.	ructions beyond those currently active in its pipeline. If nd of valid memory, then the CPU may receive an invalid					
Workaround	M1, GS3 – The prefetch queue is 8 x16 words in depth. Therefore, code should not come within 8 words of the end of valid memory. Prefetching across the boundary between two valid memory blocks is all right.						
	Example 1: M1 ends at address 0x7FF and is not followed by another memory block. Code in M1 should be stored no farther than address 0x7F7. Addresses 0x7F8–0x7FF should not be used for code.						
	Example 2: M0 ends at address 0x3FF and valid memory (M1) follows it. Code in M0 be stored up to and including address 0x3FF. Code can also cross into M1, up to an including address 0x7F7.						
	Flash – The prefetch queue is 16 x16 words in depth. Therefore, code should not come within 16 words of the end of valid memory; otherwise, it generates a Flash ECC uncorrectable error.						
	Table 3-3. Memories Impacted by Advisory						
	MEMORY TYPE	ADDRESSES IMPACTED					
	M1	0x0000 07F8–0x0000 07FF					
	GS3	0x0000 C7F8–0x0000 C7FF					
	Flash	0x0008 FFF0-0x0008 FFFF					

Advisory	SYSTEM: HIC Illegal Read Error Flag Does not Get Asserted in Pagesel=0 Mode						
Revisions Affected	0, A						
Details	When a Host Read access is initiated to the same address of a pending write location (an illegal access sequence), the Illegal Read error flag does not get asserted in Pagesel=0 Mode. The error flag gets set for the same sequence in Pagesel=1 mode. The impact is low since it is an illegal sequence and SW is not expected to initiate a read to a write-pending location in the regular application flow.						
Workaround	None						
Advisory	SYSTEM: Multiple Successive Writes to CLKSRCCTL1 Can Cause a System Hang						
Revisions Affected	0, A						
Details	When the CLKSRCCTL1 register is written more than once without delay between writes, the system can hang and can only be recovered by an external XRSn reset or Watchdog reset. The occurrence of this condition depends on the clock ratio between SYSCLK and the clock selected by OSCCLKSRCSEL, and may not occur every time.						
	If this issue is encountered while using the debugger, then after hitting pause, the program counter will be at the Boot ROM reset vector.						
	Implementing the workaround will avoid this condition for any SYSCLK to OSCCLK ratio.						
Workaround	Add a software delay of 300 SYSCLK cycles using an NOP instruction after every write to the CLKSRCCTL1 register.						
	ClkCfgRegs.CLKSRCCTL1.bit.INTOSC20FF=0; asm(" RPT #250 NOP");// Turn on INTOSC2 // Delay of 250 SYSCLK Cycles // Delay of 50 SYSCLK Cyclesasm(" RPT #50 NOP");// Delay of 50 SYSCLK CyclesClkCfgRegs.CLKSRCCTL1.bit.OSCCLKSRCSEL = 0; asm(" RPT #250 NOP");// Clk Src = INTOSC2 // Delay of 250 SYSCLK Cyclesasm(" RPT #50 NOP");// Delay of 50 SYSCLK Cycles						

C2000Ware_3_00_00_00 and later revisions will have this workaround implemented.



Advisory	Avoiding Spurious Interrupts While Using HWBIST
Revisions Affected	0, A
Details	HWBIST has the capability to log interrupts that are received while the CPU is under test and re-issue them after HWBIST completes. Interrupts that are received in the clock cycle before the interrupt logging is enabled will be executed before the HWBIST runs. In the next cycle, once interrupt logging is enabled, interrupts will be logged and re-issued once the HWBIST completes.
	The interrupt events for CPU Timer 1 and CPU Timer 2 are valid for 2 SYSCLK cycles. If the first cycle happens a cycle before interrupt logging is enabled and the second cycle coincides with the enabling of interrupt logging, the interrupt will be executed once before the logging (clearing the CPU Timer TCR.TIF flag), but then will be logged by the interrupt logger and triggered again after HWBIST completes. Since the TCR.TIF flag was already cleared by the previous ISR, this is an unexpected spurious interrupt.
	Note that this scenario is only applicable to the non-PIE CPU Timer interrupts. The CPU Timer 0 interrupt is managed by the PIE and its pulse width is only one SYSCLK cycle.
Workaround	Disable CPU Timer 1 and 2 interrupts before enabling interrupt logging and restore them later. This workaround is already implemented in the C2000 Software Diagnostic Library in the stl_hwbist_s.asm file. The steps are:
	 Clear the timer interrupt enable bit TCR.TIE for CPU Timers 1 and 2. Run normal HWBIST sequence: save registers, enable interrupt logging, run HWBIST, restore registers, end interrupt logging. Check if the CPU Timers' TCR.TIF flags are set. If the flags are set, set the corresponding CPU IFR bit to trigger the interrupt.

4. Restore TCR.TIE.

_

Advisory	PLL Reference Clock Lost Detection: Missing Clock Flag may be Incorrectly Activated	
Revisions Affected	0, A	
Details	The register bit SYSPLLSTS.REF_LOSTS may be incorrectly set, falsely indicating a reference clock loss.	
Workaround	Do not use the PLL Reference Clock Lost Detection feature. As an alternative, use the Missing Clock Detect (MCD) feature or the Dual-Clock Comparator (DCC) to detect reference clock loss.	
	 For the MCD method, refer to C2000Ware example sysctl_ex1_missing_clock_detection under the sysctl folder. For the DCC method, refer to C2000Ware example dcc_ex4_clock_fail_detect under the dcc folder. 	



4 Silicon Revision 0 Usage Notes and Advisories

4.1 Silicon Revision 0 Usage Notes

Silicon revision-applicable usage notes have been found on a later silicon revision. For more details, see Silicon Revision A Usage Notes.

4.2 Silicon Revision 0 Advisories

Silicon revision-applicable advisories have been found on a later silicon revision. For more details, see Silicon Revision A Advisories.

Advisory	ePWM: Event Latch (DCxEVTxLAT) of "DC Event-Based CBC Trip" May not Extend Trigger Pulse as Expected When Asynchronous Path is Selected	
Revision Affected	0	
Details	DCxEVTxLAT may lose the captured trigger event for an asynchronous input upon deassertion. When an asynchronous trigger is deasserted, it is expected that the flop holds the value until there is a Clear event. Since the trigger is asynchronous with respect to the clock of the flop, there is a possibility that the flop may get cleared during deassertion. This would result in a loss of event latch function.	
Workaround	None	



Page

5 Documentation Support

For device-specific data sheets and related documentation, visit the TI web site at: https://www.ti.com.

For more information regarding the TMS320F28002x devices, see the following documents:

- TMS320F28002x Real-Time Microcontrollers data sheet
- TMS320F28002x Real-Time Microcontrollers Technical Reference Manual

6 Trademarks

C2000[™] is a trademark of Texas Instruments. All trademarks are the property of their respective owners.

7 Revision History

Changes from September 17, 2022 to February 8, 2024 (from Revision B (September 2022) to Revision C (February 2024))

		-
•	Added Security: The primary layer of defense is securing the boundary of the chip, which begins with	
	enabling JTAGLOCK and Zero-pin Boot to Flash feature Usage Note	6
•	Added I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation advisory	17
•	Added Avoiding Spurious Interrupts While Using HWBIST advisory	22

Added PLL Reference Clock Lost Detection: Missing Clock Flag may be Incorrectly Activated advisory.......23

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2024, Texas Instruments Incorporated